

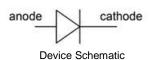
Product Summary

Vrrm (V)	lo (A)	VF Max (V)	I _R Max (μA)
40	4.0	0.62	150

Description and Applications

The SDT4U40CP3 is a 40-volt 4A trench Schottky barrier rectifier that is optimized for low forward voltage drop and low leakage current, housed in a compact chip scale package (CSP) that occupies only 1.28mm² board space with low profile. The low thermal resistance enables designers to meet design challenges of increasing efficiency whilst at the same time reducing board space. It is ideally suited for use in portable applications as a:

- Blocking Diode
- Boost Diode
- Switching Diode
- Reverse Protection Diode

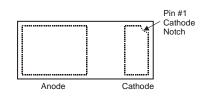


Features and Benefits

- Low forward voltage (VF) minimizes conduction losses and improves efficiency.
- Reduced high temperature reverse leakage; Increased reliability against thermal runaway failure in high temperature operation.
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. <u>https://www.diodes.com/quality/product-definitions/</u>

Mechanical Data

- Package: X3-DSN1608-2
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method 208 @4
- Polarity: Cathode Dot
- Weight: 0.001 grams (Approximate)



Ordering Information (Note 4)

Part Number	Paakaga	Packing		
	Package	Qty.	Carrier	
SDT4U40CP3-7B	X3-DSN1608-2	10,000	Tape & Reel	

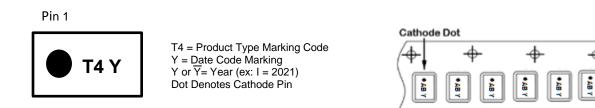
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



Date Code Key

Notes:

Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	Н		J	K	L	М	Ν	0	Р	R	S	Т



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	Vrrm	40	V
Average Rectified Output Current	lo	4.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	IFSM	28	A
ESD (Human Body Model) ESD (Machine Model)	ESD	8 0.4	kV

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{0JA}	150	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	Reja	50	°C/W
Typical Thermal Resistance Junction to Case (Note 5)	Rejc	35	°C/W
Typical Thermal Resistance Junction to Case (Note 6)	Rejc	10	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

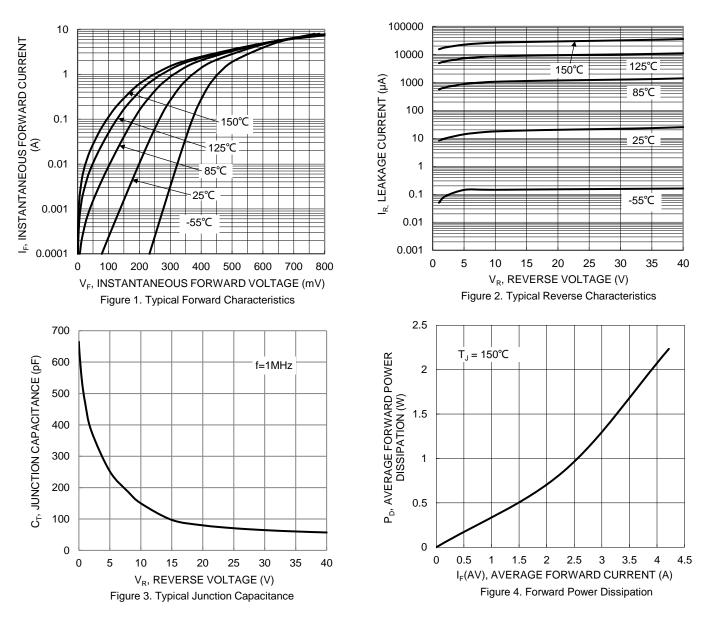
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Valtage Drop	Vf	_	0.44	0.50	V	I⊧ = 2.0A, TJ = +25°C
Forward Voltage Drop		_	0.56	0.62		IF = 4.0A, TJ = +25°C
Reverse Current (Note 7)	IR	_	40	150	μA	V _R = 40V, T _J = +25°C
Junction Capacitance	Ст	_	285	_	pF	V _R = 4V, f = 1.0MHz

Notes:

Device mounted on FR-4 PCB, 2oz. copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.
Device mounted on 1inch sq. copper pad, 2oz.
Short duration pulse test used to minimize self-heating effect.



SDT4U40CP3

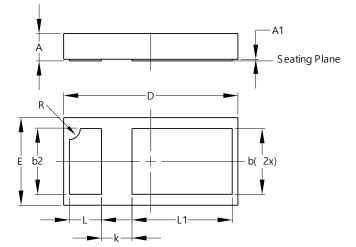




Package Outline Dimensions (Note 8)

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-DSN1608-2



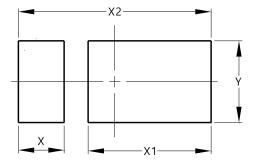
	X3-DSN1608-2								
Dim	Min	Max	Тур						
Α	0.20	0.30	0.25						
A1		0.02							
b	0.55	0.65	0.60						
b2	0.55	0.65	0.60						
D	1.56	1.64	1.60						
E	0.76	0.84	0.80						
k			0.282						
L	0.25	0.35	0.30						
L1	0.90	1.00	0.95						
R			0.10						
	All Dimensions in mm								

Note 8: Device side walls are electrically active bare silicon. Avoid contact of solder or flux on the side walls during the PCB assembly process.

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-DSN1608-2



Dimensions	Value (in mm)
Х	0.385
X1	1.035
X2	1.622
Y	0.690



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